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## About the company

Qplox is a fast-growing company offering test and automation engineering. Headquartered in Leuven, with offices in Barcelona and Eindhoven.

Our clients are major multinational enterprises and local companies from automotive, semiconductors, RF, consumer electronics.... Our Test automation group offers a one stop shop for design of automated test benches, system integration production, lab automation and data acquisition systems, with a growing focus in IoT sensor networks.

Our consultancy department offers services in RF, semiconductors and electronics design and test, as well as on the crossing roads of Nanotechnology, Bio-Science Engineering and Biotechnology.

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## Job Description

As an IC Package Design Engineer, your task is to optimize the design of an integrated circuit (IC) package to enhance its performance and reliability. You will be working on a project that involves designing a package for a high-speed device with specific requirements.

### The assignment

Your assignment consists of the following tasks:

- **Package Selection and Analysis** Select an appropriate IC package type based on the given specifications and IC requirements. Perform a comprehensive analysis of the chosen package's electrical, thermal, and mechanical characteristics. Identify any limitations or potential issues that may arise during the design process.
- **Electrical Performance Optimization** Optimize the electrical performance of the IC package by focusing on signal integrity, power integrity, and electromagnetic compatibility (EMC). Analyze the routing, parasitic effects, and noise issues associated with the package. Propose design modifications or enhancements to improve electrical performance.
- **Design for Manufacturability and Cost Optimization** Consider manufacturability and cost optimization aspects of the IC package design. Review the design for compatibility with manufacturing processes, assembly requirements, and materials availability. Suggest design modifications to streamline the manufacturing process while maintaining or reducing overall costs.
- **Documentation and Reporting** Produce a comprehensive report summarizing your analysis, design modifications, and optimization recommendations for the IC package. Include detailed diagrams, simulations, calculations, and experimental results where applicable. Clearly communicate the rationale behind your design decisions and their potential impact on the IC's performance and reliability.

**Location: Leuven**

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## Candidate Description

- Knowledge in Cadence layout tool.
  - Knowledge in Ansys tool.
  - To be able to communicate in English is a must.
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## We offer

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An attractive salary package with extra benefits. A high tech, multicultural and young ambient. A fast track in a growing company. Formation in multidisciplinary environment plenty of learning opportunities.

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## Contact

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Send your CV and application letter to [jobs@qplox.com](mailto:jobs@qplox.com) with the subject “**IC Package Design Engineer**”.

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